## **AMENDMENT TO THE SPECIFICATION**

1. Please add the following paragraph, prior to the first line of the application, stating:

This application claims the priority of International Patent Application PCT/DE03/00964 filed on March 24, 2003, which claims priority to German Patent Application 102 17 567.5 filed on April 19, 2002 and is incorporated herein by reference.

- 2. Please delete the paragraph on page 4, ll. 8-11.
- 3. Please substitute the following paragraph for the second paragraph on page 13, beginning at line 13 as follows:

Provision may also be made for the bars 1a to 1j and the bars 2a to 2j to have different lengths. What is fundamental, however, is that the sums The sum of the lengths of adjacent bars on the first and second metallization planes are respectively may be greater than the distance b between the metallization planes. This ensures that surface regions of the side faces of the bars 1a to 1j on the first metallization plane 1 and surface regions of the side face of the respectively adjacent bars 2a to 2j on the second metallization plane 2 are always opposite one another and this creates a capacitance surface which makes a contribution to the useful capacitance. In the exemplary embodiment, the plate 2 with the bars 1a to 1j, which is further from the semiconductor substrate, has a minimum parasitic capacitance with respect to the semiconductor substrate.